



Product Change Notification / JAON-24XWVA797

Date:

26-Oct-2021

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4823 Final Notice: Qualification of MTAI as an additional final test site for selected SST26VF064B, and SST26VF064BA device families available in 16L SOIC (0.300in) package.

Affected CPNs:

[JAON-24XWVA797_Affected_CPN_10262021.pdf](#)

[JAON-24XWVA797_Affected_CPN_10262021.csv](#)

Notification Text:

PCN Status:Final notification.

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of MTAI as an additional final test site for selected SST26VF064B, and SST26VF064BA device families available in 16L SOIC (0.300in) package.

Pre and Post Change Summary:

	Pre Change	Post Change	
Final Test Site	King Yuan Electronics Company, Limited (KYE)	King Yuan Electronics Company, Limited	Microchip Technology Thailand

			(KYE)	(HQ) (MTAI)
Base Quantity Multiple (BQM)	Tape and Reel	1000	1000	1000
	Tube	47	47	47
Pin Orientation	Tape and Reel	Quadrant 1	Quadrant 1	Quadrant 1
	Tube	See pre and post change comparison.		
Carrier tape		No dimensional changes. See pre and post change comparison.		
Cover Tape		Minor dimensional changes. See pre and post change comparison.		
Plastic Reel		Minor dimensional changes. See pre and post change comparison.		
Packing Method		See pre and post change comparison.		

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve manufacturability and on-time delivery performance by qualifying MTAI as an additional final test site.

Change Implementation Status:In Progress

Estimated First Ship Date:November 05, 2021 (date code: 2145)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	October 2021					November 2021				
Workweek	40	41	42	43	44	45	46	47	48	49
Initial PCN Issue Date	X									
Qual Report Availability					X					
Final PCN Issue Date					X					
Estimated Implementation Date						X				

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: **October 1, 2021:** Issued initial notification. **October 4, 2021:** Re-issued initial notification with updated qualification plan. **October 26, 2021:** issued final notification. Attached the qualification report. Provided estimated first ship date to be on November 05, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-24XWVA797_Qual Report.pdf](#)

[PCN_JAON-24XWVA797_Pre and Post Change_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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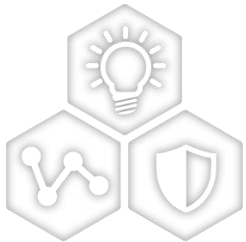
Affected Catalog Part Numbers (CPN)

SST26VF064B-104I/SO
SST26VF064BA-104I/SO
SST26VF064B-104V/SO
SST26VF064BT-104V/SO
SST26VF064BT-104I/SO
SST26VF064BAT-104I/SO

CCB 4823
Pre and Post Change Summary
PCN# JAON-24XWVA797

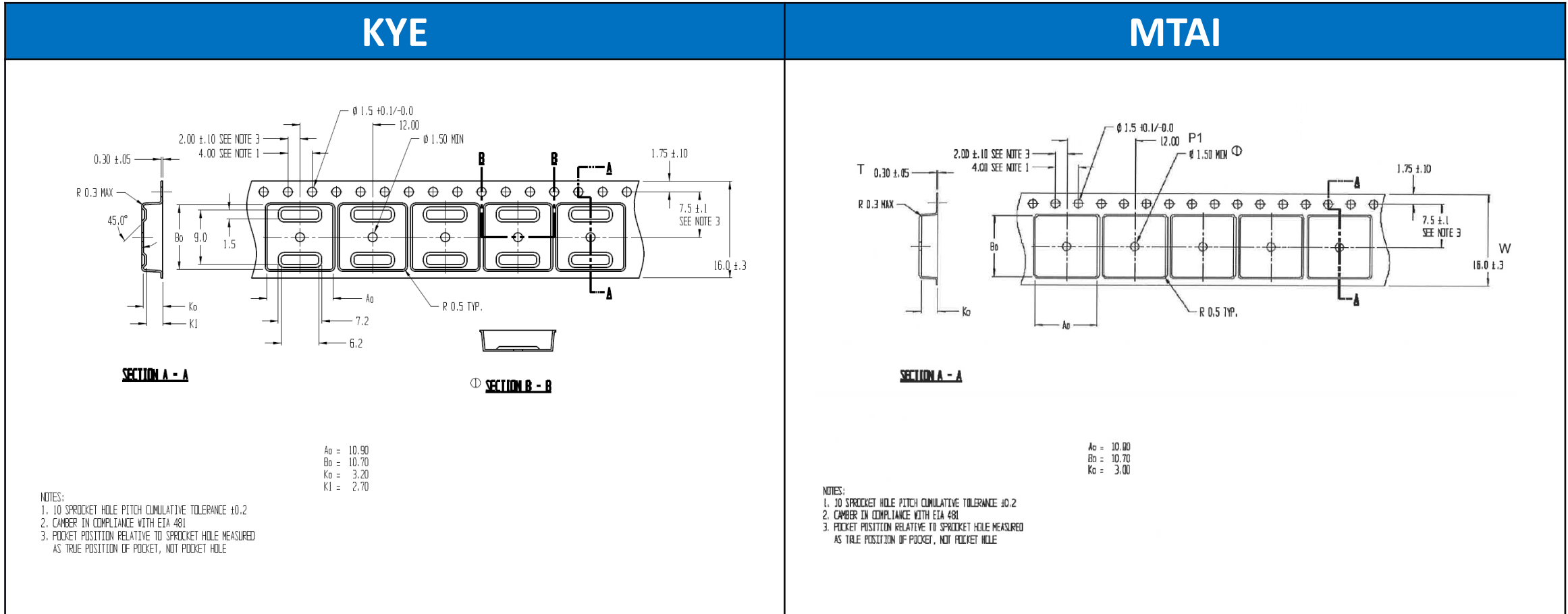


A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



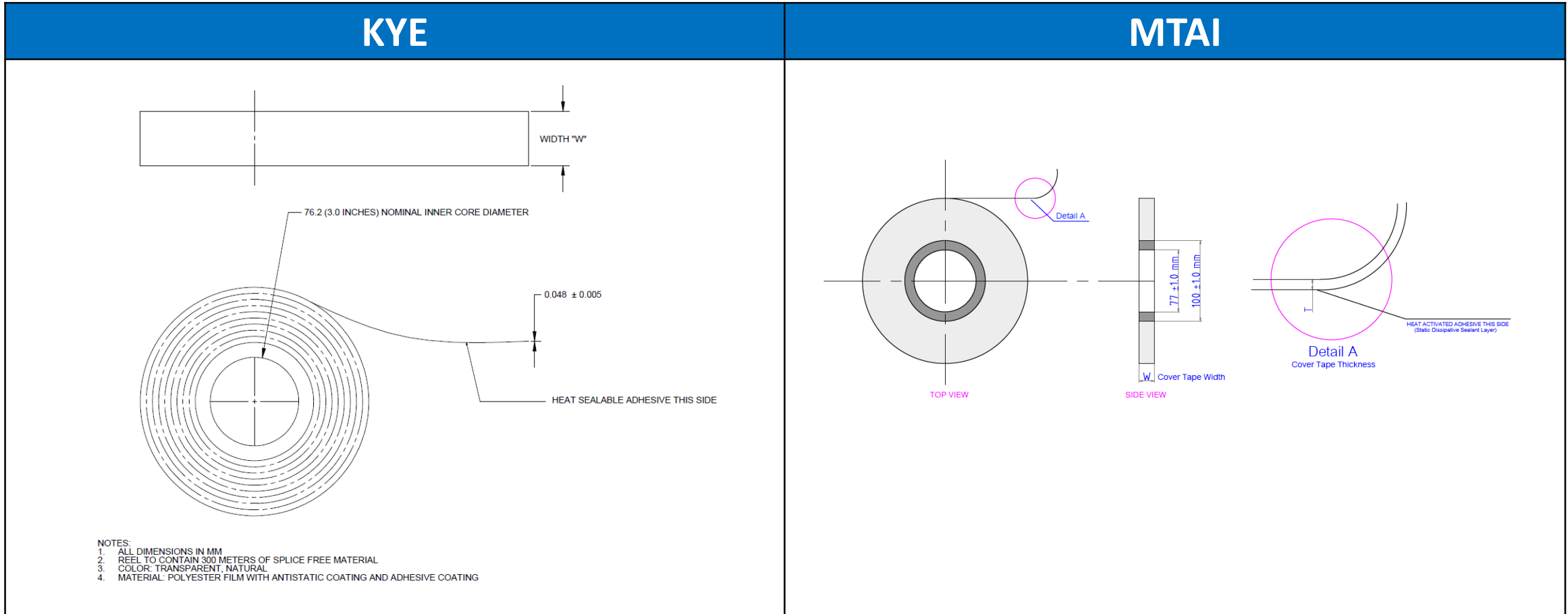
SMART | CONNECTED | SECURE

Pre and Post Change Summary – Carrier Tape



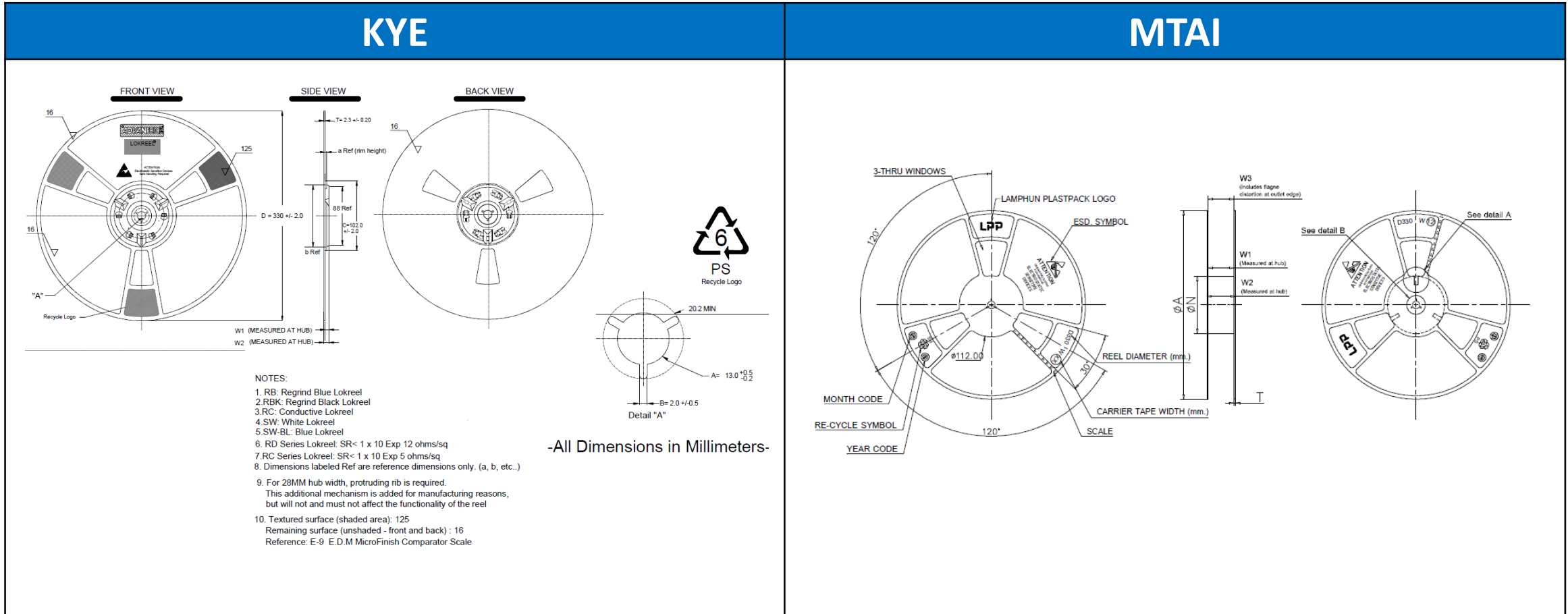
Plant	W (mm.)	P (mm.)	A0 (mm.)	B0 (mm.)	K0 (mm.)	K1 (mm.)	Thickness	BQM	Pin1
MTAI	16.00 ± 0.30	12.00 ± 0.10	10.90 ± 0.10	10.70 ± 0.10	3.00 ± 0.10	-	0.30 ± 0.05	1000	Quadrant 1
KYE	16.00 ± 0.30	12.00 ± 0.10	10.90 ± 0.10	10.70 ± 0.10	3.20 ± 0.10	2.70 ± 0.10	0.30 ± 0.05	1000	Quadrant 1

Pre and Post Change Summary – Cover Tape



Plant	Width W (mm.)	Thickness T (mm.)	Color	Sealing Methodology
MTAI	13.3 ± 0.1	0.050 ± 0.010	Clear	Heat Seal
KYE	13.3 ± 0.1	0.048 ± 0.005	Clear	Heat Seal

Pre and Post Change Summary – Plastic Reel



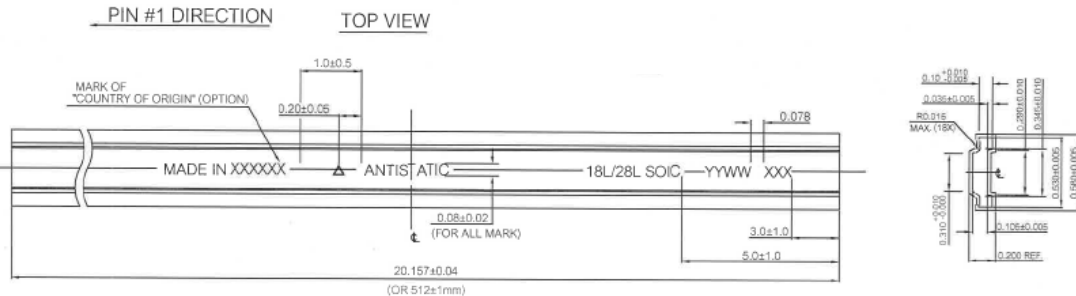
Plant	Reel Diameter (mm.)	Reel Hub Size (mm)	Reel Width Max (mm.)	Color
MTAI	330 ±2.0	100 ±2.0	22.40	Dark Blue
KYE	330 ±2.0	102±2.0	8.4+0.3/-0.2 + 8.4+0.3/-0.2	Regrind Blue

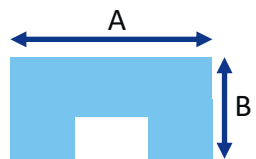
Pre and Post Change Summary – Tape and Reel Packing Method



Plant	MSL Level	Desiccant	Humidity Indicator Card	Baking Condition
MTAI	MSL-3	2 units	1 pcs	4 hours @125°C
KYE	MSL-3	2 units	1 pcs	4 hours @ 125°C

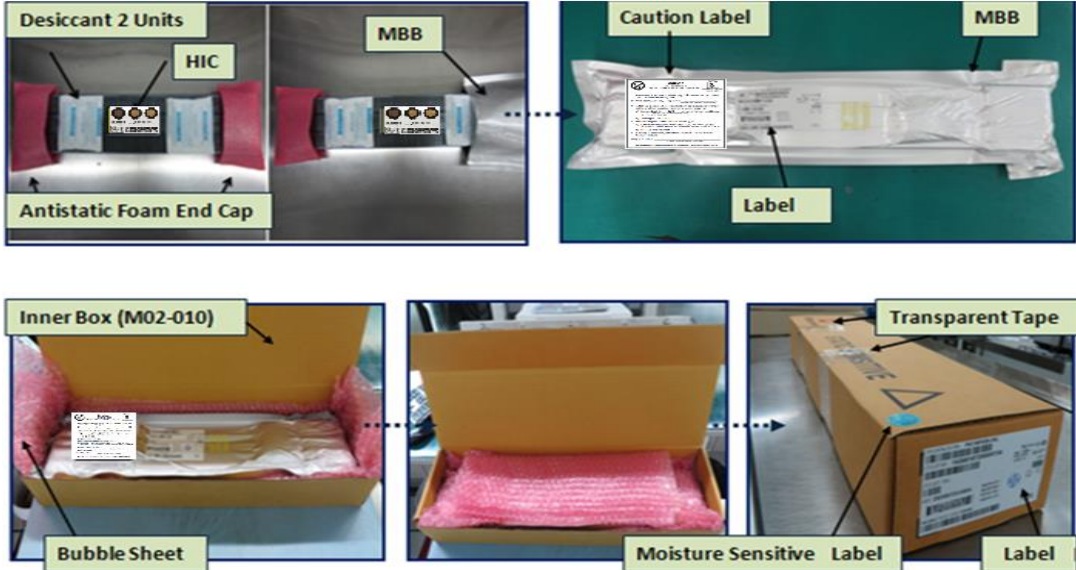
Pre and Post Change Summary – Tube

KYE	MTAI
<p style="text-align: center;">Not Applicable Tested at KYE but Scan & Packed at MTAI</p>	



Plant	Tube Length (in)	Dimension A (in)	Dimension B (in)	Tube Color	BQM Per media
MTAI	20.157 ± 0.04	0.580 ± 0.005	0.200 ± 0.01	Clear	47
KYE	N/A				

Pre and Post Change Summary – Tube Packing Method

KYE	MTAI
<p data-bbox="275 616 1065 714">Not Applicable Tested at KYE but Scan & Packed at MTAI</p>	 <p>The MTAI process involves the following steps and components:</p> <ul style="list-style-type: none">Two units are placed in a tube with desiccant and HIC.The tube is sealed with antistatic foam end caps and MBB.The tube is placed in an inner box (M02-010) with a bubble sheet.The inner box is placed in a larger box with a moisture sensitive label.The larger box is sealed with transparent tape and a final label.



MICROCHIP

QUALIFICATION REPORT SUMMARY

PCN #: JAON-24XWVA797

Date

September 23, 2021

Qualification of MTAI as an additional final test site for selected SST26VF064B, and SST26VF064BA device families available in 16L SOIC (0.300in) package.

Purpose: Qualification of MTAI as an additional final test site for selected SST26VF064B, and SST26VF064BA device families available in 16L SOIC (0.300in) package.

CCB No.: 4823

Test / Evaluation	Test Conditions / Parameters	Results
Destination Final Test Site Correlation	1.5K units through flow <ul style="list-style-type: none"><li data-bbox="651 531 1057 594">• 100% FT_KGD@25C at MTAI Acceptance: Production Yield<li data-bbox="651 625 1036 747">• 100% QCP@25C at MTAI Acceptance: zero failure or reasonable Electrical Failure Analysis (EFA)	Passed